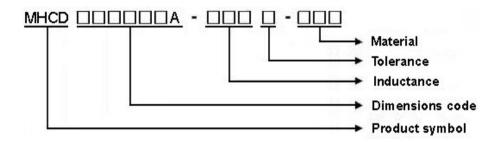


Halogen Free & RoHs Compliance

SPECIFICATION FOR APPROVAL

CUSTOMER:					
CUSTOMER P/N:					
OUR DWG No:					
QUANTITY:	0	Pcs.	DATE :	2014/06/09	
ITEM:		— Мнсе)252010A-	 R47M-A8L	
	SP	ECIFIC/	ATION		
		<u>CCEPTEI</u>			
COMPONENT					
ENGINEER					
ELECTRICAL					
ENGINEER	1				
MECHANICAL					
ENGINEER	<u> </u>				
APPROVED					
REJECTED					
奇力新電子股份有限公司 Chilisin Electronic sCorp No. 29, Alley 301, Tehhsin Rd. Hukou, Hsinchu 303, Taiwan TEL: +886-3-599-2646 FAX: +886-3-599-9176 E-mail: sales@chilisin.com.tw	.,	Chilis No. 7 Area Guar TEL FAX		Dongguan) Co., Ltd. Yuliangwei Administration Dongguan City, -0251~3 3-0232	
奇力新電子(河南)有限公司 Chilisin Electronics (Henan) Co., Ltd. XiuWu Xian, industry gathering area JiaoZuo, Henan China Postal Code:454350 TEL:+86-391-717-0682 FAX:+86-391-717-0666					
DRAWN BY 張鈺雯 chang.yuwen		CHECKED 溫美玲 li		APPROVED BY 張鈺雯 chang.yuwen	

- 1 Scope: This specification applies to Alloy Molding power inductors
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-4~0~\mathrm{C}\!\sim\!1~2~5~\mathrm{C}$ (Including self - temperature rise)

Storage Temperature: $-4~0~\%\sim1~2~5~\%$ (after PCB)

-5 $^{\circ}$ $^{\circ}$ $^{\circ}$ 3 5 $^{\circ}$ 7, Humidity 4 5 $^{\circ}$ $^{\circ}$ 8 5 $^{\circ}$ 6 (before PCB)

4 Marking:

No Marking

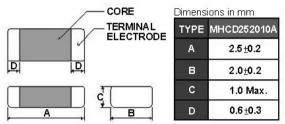
5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35 $^\circ$ C)	20±2 ℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH



MHCD252010A Series Specification

6 Configuration and Dimensions:



7 ELECTRICAL CHARACTERISTICS :

Part No.	Inductance (uH)	Test Freq.	Irms(A) Max.(Typ)	Isat(A) Max.(Typ)	RDC(mΩ) Max.(Typ)	Tolerance (±%)	
MHCD252010A-R47M-A8L	0.47	2MHz,0.2V	3.4(3.9)	4.2(4.7)	35(29)	20	

NOTE:

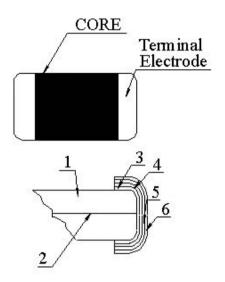
- 1.Operating temperature range $-4~0~\text{C}\sim 1~2~5~\text{C}$ (Including self temperature rise)
- 2.Irms DC current (A) that will cause an approximate ΔT of 40°C.
- 3.Isat DC current (A) that will cause Lo to drop approximately 30%
- 4.All test data is referenced to 25℃ ambient



MHCD252010A Series Specification

8 MHCD252010A Series

8.1 Construction:



8.2 Material List:

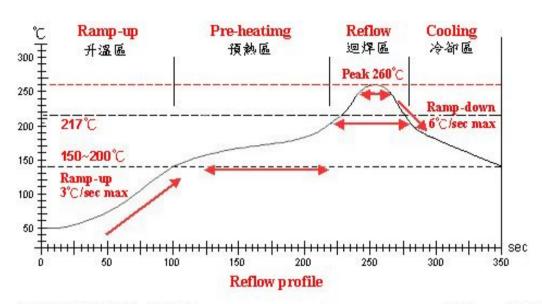
NO	Part	Description
1	Core	Metal Power
2	Wire	Copper wire
3	Sputter/Plating	Cu
4	Silver Electrode	Ag
5	Plating	Ni
6	Plating	Sn



MHCD252010A Series Specification

1.10	lechanical Performance Item	Specification		Test Method	
1 1	Flexure Strength	The forces applied on the right	Toot de	evice shall be soldered on the substrate	
- 1 - 1	Flexure Strength	conditions must not damage		ate Dimension: 100x40x1.6mm	
		the terminal electrode and the			
		ferrite		110	
		lemie	Keepii	g Time: 30sec	
-1-2	Vibration	1	Tost de	evice shall be soldered on the substrate	
- 1-2	Vibration			tion Frequency: 10 to 55 to 10Hz for 1min	
				ude: 1.5mm	
1 2	Desistance to Coldering Uset	Annogrange: No damage		2hrs for each axis (X, Y & Z), total 6hrs	
- 1-3	Resistance to Soldering Heat	1 · ·		ating: 150°C, 1min	
		More than 75% of the terminal		Composition: Sn/Ag3.0/Cu0.5(Pb-Free)	
		electrode should be covered		Temperature: 260±5°C	
		with solder.	Immer	sion Time: 10±1sec	
		Inductance: within ±20% of			
		initial value			
-1-4	Solder ability	The electrodes shall be at		ating: 150°C, 1min	
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free		
		solder coating		Temperature: 245±5°C	
			Immer	sion Time: 4±1sec	
-1-5	erminal Strength Test No split termination			evice shall be soldered on the substrate,	
		Chip	then apply a force in the direction of the		
		F	Force		
			Keepin	g Time: 10±1sec	
		Mounting Pad			
_2 E	nvironmental Performance		1		
		I Specification		Test Method	
No	Item	Specification	_		
No	Item Temperature Cycle	Appearance: No damage	One cy	rcle:	
No		Appearance: No damage Inductance:within±20% of	Step	rcle: \\ \	
No		Appearance: No damage	Step 1	rcle: Temperature (°C) // Time (min -40±3 // 30	
No		Appearance: No damage Inductance:within±20% of	Step 1 2	Temperature (°C) / Time (min -40±3 30 25±2 / 2	
No		Appearance: No damage Inductance:within±20% of	Step 1	rcle: Temperature (°C) // Time (min -40±3 // 30	
No		Appearance: No damage Inductance:within±20% of	Step 1 2 3 4	Temperature (°C) / Time (min -40±3	
No		Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total:	Temperature (°C) // Time (min -40±3 // 30 // 25±2 // 2 // 125±3 // 30 // 25±2 // 2 // 2 // 100cycles	
No -2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total:	Temperature (°C) // Time (min -40±3 // 30 // 25±2 // 2 // 125±3 // 30 // 25±2 // 2 // 2 // 100cycles	
No -2-1		Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu	Temperature (°C) // Time (min -40±3 // 30 // 25±2 // 2 // 125±3 // 30 // 25±2 // 2 // 2 // 100cycles	
No -2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ	rcle:	
No -2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ	rcle:	
No -2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ Measu	rcle: Temperature (°C) Time (minum) -40 ± 3 30 25 ± 2 2 125 ± 3 30 25 ± 2 2 2 100cycles red after exposure in the room condition for 24h rature: $60\pm2^{\circ}$ C e Humidity: $90 \sim 95\%$ / Time: 500 hrs	
No -2-1	Temperature Cycle Humidity Resistance High	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ Measu Tempe	rcle:	
No -2-1	Temperature Cycle Humidity Resistance	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ Measu Tempe Relativ	rcle: Temperature (°C) Time (mi -40±3 30 25±2 125±3 30 25±2 2 100cycles red after exposure in the room condition for 24h rature: $60\pm2^{\circ}$ C e Humidity: $90 \sim 95\%$ / Time: 500hrs red after exposure in the room condition for 12h rature: $85\pm3^{\circ}$ C e Humidity: 0% / Time: 500hrs	
-2-1 -2-3	Temperature Cycle Humidity Resistance High Temperature Resistance	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ Measu Tempe Relativ Measu	rcle: Temperature (°C) Time (mi -40±3 30 25±2 125±3 30 25±2 2 100cycles red after exposure in the room condition for 24h rature: $60\pm2^{\circ}$ C e Humidity: $90 \sim 95\%$ / Time: 500hrs red after exposure in the room condition for 12h rature: $85\pm3^{\circ}$ C e Humidity: 0% / Time: 500hrs red after exposure in the room condition for 12h rature: $85\pm3^{\circ}$ C e Humidity: 0% / Time: 500hrs red after exposure in the room condition for 12h	
-2-1 -2-3	Temperature Cycle Humidity Resistance High	Appearance: No damage Inductance:within±20% of	Step 1 2 3 4 Total: Measu Tempe Relativ Measu Tempe Relativ Measu Tempe Tempe Tempe Relativ Measu Tempe	rcle:	





Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
温度範圍 Temp.scope	R.T. ~150℃	150°C ~ 200°C	217℃	260±5°⊂	Peak Temp. ~ 150℃
標準時間 Time spec.	-550	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	(-)

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



11 PACKAGING

11.1 Packaging -Cover tape

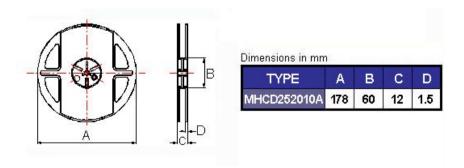
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL
MHCD252010A	V	3000

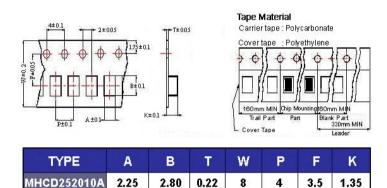
11.3 Reel Dimensions



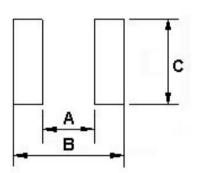


11 PACKAGING

11.4 Tape Dimensions in mm



12 Recommended Pattern



Dimensions in mm

TYPE	Α	В	O
MHCD252010A	1.2	2.8	2.0

13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)